

IN THE SPECIFICATION:

Please amend paragraph number [0001] as follows:

[0001] This application is a divisional of application Serial No. 09/978,480, filed October 17, 2001, ~~pending,~~ now U.S. Patent 6,691,696, issued February 17, 2004, which is a divisional of application Serial No. 09/753,159, filed January 2, 2001, now U.S. Patent 6,427,676, issued August 6, 2002, which is a continuation of application Serial No. 09/434,147, filed November 4, 1999, now U.S. Patent 6,196,096, issued March 6, 2001, which is a continuation of Serial No. 09/270,539, filed March 17, 1999, now U.S. Patent 6,155,247, issued December 5, 2000, which is a divisional of application Serial No. 09/069,561, filed April 29, 1998, now U.S. Patent 6,119,675, issued September 19, 2000, which is a divisional of application Serial No. 08/747,299, filed November 12, 1996, now U.S. Patent 6,250,192, issued June 26, 2001.

Please amend paragraph number [0015] as follows:

[0015] FIG. 4 is a schematic view of a ~~first~~-prior art silicon semiconductor wafer having a conventional configuration to be diced with the wafer saw of the present invention;

Please amend paragraph number [0016] as follows:

[0016] FIG. 5 is a schematic view of a ~~second~~-silicon semiconductor wafer having variously sized semiconductor devices therein to be diced with the wafer saw of the present invention;

Please amend paragraph number [0018] as follows:

[0018] FIG. 7 is a schematic view of a ~~third~~-silicon semiconductor wafer having variously sized semiconductor devices therein to be diced with the wafer saw of the present invention;

Please amend paragraph number [0023] as follows:

[0023] Before proceeding further, it will be understood and appreciated that design and fabrication of a wafer saw according to the invention having the previously referenced, multi-indexing capabilities, independent lateral blade translation and independent blade raising or elevation ~~is~~ are within the ability of one of ordinary skill in the art and that, likewise, the control of such a device to effect the multiple-indexing (whether in units of fixed increments or otherwise), lateral blade translation and blade elevation may be effected by suitable programming of the software-controlled operating system, as known in the art. Accordingly, no further description of hardware components or of a control system to effectuate operation of the apparatus of the invention is necessary.

Please amend paragraph number [0025] as follows:

[0025] As illustrated in FIG. 6, a wafer saw 70 according to the present invention is shown having two blades 72 and 74, one of which is independently raisable (as indicated by an arrow) relative to the other. As used herein, the term "raisable" includes vertical translation either up or down. Such a configuration may be beneficial for situations where the distance between adjacent streets is less than the minimum lateral achievable distance between blades 72 and 74, or only a single column of narrow dice is to be cut, such as at the edge of a wafer. Thus, when cutting a wafer 80, as better illustrated in FIG. 7, the two blades 72 and 74 can make a first pass along streets 82 and 83. One blade 72 can then be raised, the wafer 80 indexed relative to the unraised blade 74 and a second pass performed along street 84 only. Blade 72 can then be lowered and the wafer 80 indexed for cutting along streets 85 and 86. The process can be repeated for streets 87 (single-blade pass), 88, and 89 (double-blade pass). The elevation mechanism 76 for blade 72 may comprise a stepper motor, a precision-g geared hydraulic or electric mechanism, a pivotable arm which is electrically, hydraulically or pneumatically powered, or by other means well known in the art.

Please amend paragraph number [0028] as follows:

[0028] For example, illustrated in FIG. 8, a semiconductor substrate 100 or portion thereof may have traces 102 formed thereon by electrodeposition techniques that require connection of a plurality of traces 102 through a tie bar 104. A two-blade saw in accordance with the present invention may be employed to simultaneously scribe substrate 100 along parallel lines 106 and 108 flanking a street 110 in order to sever tie bars 104 of adjacent substrate segments 112 from their associated traces 102. Following such severance, the two columns of adjacent substrate segments 112 (corresponding to what would be termed “dice” if integrated circuits were formed thereon) are completely severed along street 110 after the two-blade saw is indexed for alignment of one blade therewith, and the other blade raised out of contact with substrate 100. Subsequently, when either the saw or the substrate carrier is rotated 90°, singulation of the segments 112 is completed along mutually parallel streets 114. Thus, substrate segments 112 for test or packaging purposes may be fabricated more efficiently in the same manner as dice and in the same sizes and shapes: